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2013年10月

# **FAN7390**

# 高电流、高端与低端、栅极驱动 IC

#### 特性

- 浮动通道可实现高达 +600V 的自举运行
- 所有通道的拉电流和灌电流驱动能力为 4.5A/4.5A
- 共模 dv/dt 噪声消除电路
- 两个通道均内置欠压闭锁功能
- 适用于两个通道的匹配传播延迟
- 逻辑地 (V<sub>SS</sub>) 和功率 (COM) 接地 +/- 7V 偏压
- 兼容 3.3V 和 5V 输入逻辑
- 输出与输入同相

#### 应用

- PDP 维持驱动
- HID 灯镇流器
- SMPS
- 电动机驱动

### 说明

FAN7390 是单片高端和低端栅极驱动 IC,可以驱动工作 电压最高达 +600V 的高速 MOSFET 和 IGBT。它具有缓 冲输出级,且所有 NMOS晶体管设计为具有高脉冲电流驱 动能力和最低交叉传导。

飞兆半导体的高压工艺和共模噪声消除技术,即使在较高 dv/dt 噪声环境中,也能够保证高端驱动器工作稳定。先进 的 电 平 转 换 电 路,使 高 端 栅 极 驱 动 器 在 电 源 电 压 为  $V_{BS}$ =15V 时能够承受高达  $V_{S}$ =-9.8V(典型值)正常工作。

UVLO 电路可防止驱动电路当 V<sub>DD</sub> 和 V<sub>BS</sub> 低于指定的阈值电压时发生故障。

其高电流和低输出电压跌落的特点可确保此器件适用于 PDP 维持脉冲驱动,电动机驱动,开关电源以及大功率直 流转换器等应用。

8-SOP

-5



# **Ordering Information**

器件编号	封装	工作 温度范围	包装方法
FAN7390MX	8-SOP	-40°C ~ 125°C	卷带和卷盘
FAN7390M1X	14-SOP	-40 C ~ 125 C	卷带和卷盘

# 典型应用电路

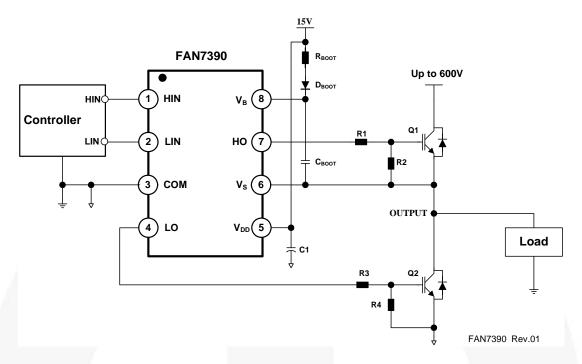


图 1. 半桥应用参考电路 (参考 8-SOP)

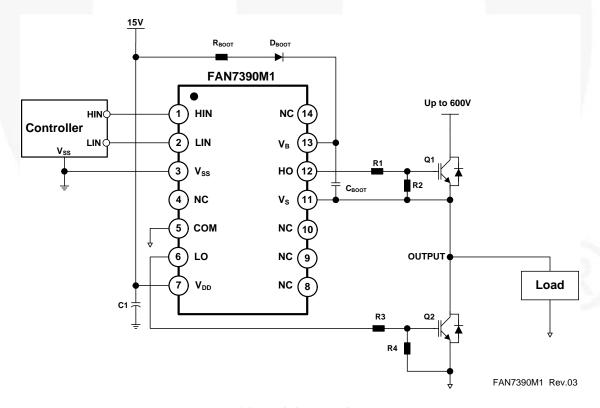


图 2. 半桥应用参考电路 (参考 14-SOP)

# 内部框图

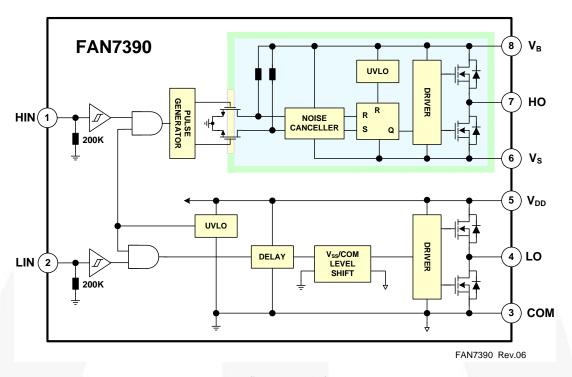


图 3. 功能模块框图 (参考 8-SOP)

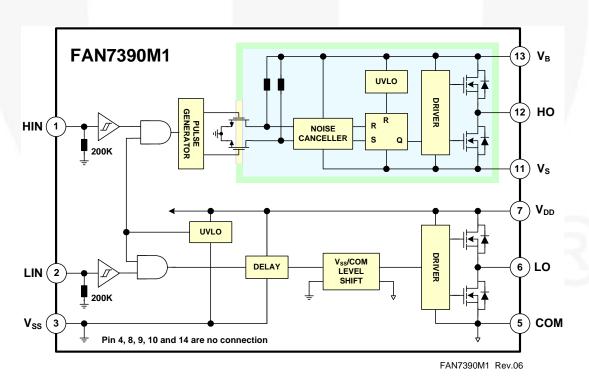


图 4. 功能模块框图 (参考 14-SOP)

# 引脚布局

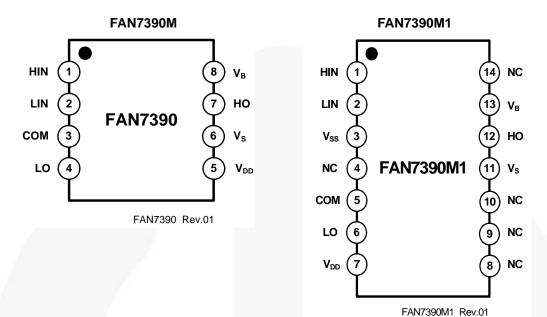


图 5. 引脚分配 (顶视图/俯视图)

# 引脚说明

8-Pin	14-Pin	名称	说明
1	1	HIN	高端栅极驱动器输出的逻辑输入
2	2	LIN	低端栅极驱动器输出的逻辑输入
	3	V <sub>SS</sub>	逻辑地 (仅适用于 FAN7390M1)
3	5	COM	低端栅极返回
4	6	LO	低端栅极输出
5	7	$V_{DD}$	低端和逻辑电路的电源电压
6	11	V <sub>S</sub>	高端浮动电源电压返回
7	12	НО	高端驱动输出
8	13	V <sub>B</sub>	高端浮动电源
	4, 8, 9, 10, 14	NC	未连接

#### 绝对最大额定值

应力超过绝对最大额定值,可能会损坏器件。在超出推荐的工作条件的情况下,该器件可能无法正常工作,所以不建议让器件在这些条件下长期工作。此外,过度暴露在高于推荐的工作条件下,会影响器件的可靠性。绝对最大额定值仅是应力规格值。除非另有说明,  $T_A=25^{\circ}C$ 。

符号	特性	最小值	最大值	单位
V <sub>S</sub>	高端浮动电源偏置电压	V <sub>B</sub> -25	V <sub>B</sub> +0.3	V
V <sub>B</sub>	高端浮动电源电压	-0.3	625.0	V
V <sub>HO</sub>	高端浮动输出电压 HO	V <sub>S</sub> -0.3	V <sub>B</sub> +0.3	V
V <sub>DD</sub>	低端和固定逻辑电源电压	-0.3	25.0	V
V <sub>LO</sub>	低端输出电压 LO	-0.3	V <sub>DD</sub> +0.3	V
V <sub>IN</sub>	逻辑输入电压 (HIN, LIN)	V <sub>SS</sub> -0.3	V <sub>DD</sub> +0.3	V
V <sub>SS</sub>	逻辑地 (仅适用于 FAN7390M1)	V <sub>DD</sub> -25	V <sub>DD</sub> +0.3	V
dV <sub>S</sub> /dt	允许的偏置电压转换速率		50	V/ns
P <sub>D</sub> <sup>(1)(2)(3)</sup>	功耗	8-SOP	0.625	W
PD( // //-/	りがた	14-SOP	1.000	VV
Δ	结至环境热阻	8-SOP	200	°C/W
$\theta_{\sf JA}$	41 生 4 先 5 性 5 性 5 性 5 性 5 性 5 性 5 性 5 性 5 性 5	14-SOP	110	C/VV
TJ	结温		+150	°C
T <sub>STG</sub>	存储温度		+150	°C

#### 注意:

- 1. 安装到 76.2 x 114.3 x 1.6mm PCB 板 (FR-4 环氧玻璃材料)。
- 2. 参考以下标准:

JESD51-2: 集成电路热测试方法环境条件 - 自然对流

JESD51-3: 含铅表面贴装封装的低有效导热系数测试板

3. 在任何情况下,都不要超过 PD。

### 推荐工作条件

推荐的操作条件表定义了器件的真实工作条件。指定推荐的工作条件,以确保器件的最佳性能达到数据表中的规格。飞兆不建议超出额定或依照绝对最大额定值进行设计。

符号	参数	最小值	最大值	单位
$V_{B}$	高端浮动电源电压	V <sub>S</sub> +10	V <sub>S</sub> +22	V
V <sub>S</sub>	高端浮动电源偏置电压	6-V <sub>DD</sub>	600	V
V <sub>HO</sub>	高端输出电压	V <sub>S</sub>	$V_{B}$	V
$V_{DD}$	低端和逻辑电源电压	10	22	V
$V_{LO}$	低端输出电压	COM	$V_{DD}$	V
V <sub>IN</sub>	逻辑输入电压 (HIN, LIN)	$V_{SS}$	$V_{DD}$	V
T <sub>A</sub>	操作环境温度	-40	+125	°C

# 电气特性

 $V_{BIAS}$  ( $V_{DD}$ , $V_{BS}$ )=15.0V, $V_{S}$ = $V_{SS}$ =COM, $T_{A}$ =25×C,除非另有说明  $V_{IL}$ 、 $V_{IH}$  和  $I_{IN}$  参数以  $V_{SS}$ /COM 作为基准,适用于各自的输入信号 HIN 和 LIN。  $V_{O}$  和  $I_{O}$  参数以 COM 和  $V_{S}$  作为基准,适用于各自的输出信号 HO 和 LO。

符号	特性	测试条件	最小值	典型值	最大值	单位
电源部分	(V <sub>DD</sub> 和V <sub>BS</sub> )		•	•		
V <sub>DDUV+</sub> V <sub>BSUV+</sub>	V <sub>DD</sub> 和 V <sub>BS</sub> 电源欠压正向阈值		8.0	8.8	9.8	
V <sub>DDUV-</sub> V <sub>BSUV-</sub>	V <sub>DD</sub> 和 V <sub>BS</sub> 电源欠压负向阈值		7.4	8.3	9.0	V
V <sub>DDUVH</sub> V <sub>BSUVH</sub>	V <sub>DD</sub> 和 V <sub>BS</sub> 电源欠压锁定滞洄电压			0.5		
I <sub>LK</sub>	偏置漏电流	$V_B=V_S=600V$			50	
$I_{QBS}$	V <sub>BS</sub> 静态电源电流	V <sub>IN</sub> =0V 或 5V		45	80	μΑ
I <sub>QDD</sub>	V <sub>DD</sub> 电源静态电流	V <sub>IN</sub> =0V 或 5V	4	75	110	
I <sub>PBS</sub>	V <sub>BS</sub> 电源静态电流	f <sub>IN</sub> =20kHz,rms 值		530	640	μA
I <sub>PDD</sub>	V <sub>DD</sub> 电源工作电流	f <sub>IN</sub> =20kHz,rms 值		530	640	μΑ
逻辑输入	部分 (HIN, LIN)					
V <sub>IH</sub>	逻辑 "1" 输入电压		2.5			V
V <sub>IL</sub>	逻辑 "0" 输入电压				1.2	V
I <sub>IN+</sub>	逻辑 "1" 输入偏置电流	V <sub>IN</sub> =5V		25	50	μA
I <sub>IN-</sub>	逻辑 "0" 输入偏置电流	V <sub>IN</sub> =0V		1.0	2.0	μΛ
R <sub>IN</sub>	输入下拉电阻		100	200		ΚΩ
栅极驱动	器输出部分(HO, LO)					
V <sub>OH</sub>	高电平输出电压, V <sub>BIAS</sub> -V <sub>O</sub>	无负载			1.0	V
V <sub>OL</sub>	低电平输出电压, V <sub>O</sub>	无负载			35	mV
I <sub>O+</sub>	输出高电平短路脉冲电流 (4)	V <sub>O</sub> =0V, V <sub>IN</sub> =5V with PW<10µs	3.5	4.5		Α
I <sub>O-</sub>	输出低电平短路脉冲电流 (4)	V <sub>O</sub> =15V, V <sub>IN</sub> =0V with PW<10µs	3.5	4.5		A
Vs	当 HIN 信号传输至 HO 时,容许 $V_S$ 引脚 负电压		- //	-9.8	-7.0	٧
V <sub>SS</sub> - COM	V <sub>SS</sub> -COM/COM-V <sub>SS</sub> 电压持久性		-7.0		7.0	V

#### 注意:

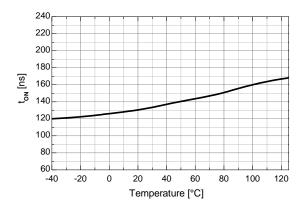
4. 参数由设计者提供。

# 动态电气特性

V<sub>BIAS</sub> (V<sub>DD</sub>, V<sub>BS</sub>)=15.0V, V<sub>S</sub>=V<sub>SS</sub>=COM=0V, C<sub>L</sub>=1000pF且 T<sub>A</sub>=25**x**C,除非另有说明。

符号	特性	测试条件	最小值	典型值	最大值	单位
t <sub>on</sub>	导通传输延时	V <sub>S</sub> =0V		140	200	w
t <sub>off</sub>	关断传输延时	V <sub>S</sub> =0V		140	200	
MT	延时匹配, HS 与 LS 导通 / 关断			0	50	ns
t <sub>r</sub>	导通上升时间			25	50	
t <sub>f</sub>	关断下降时间			20	45	

# 典型特性



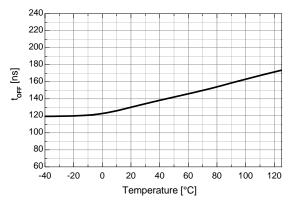
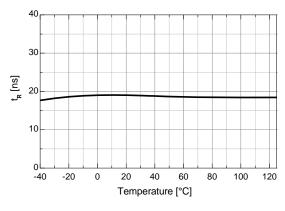


图 6. 开通传输延时与温度的关系

图 7. 关断传输延时与温度的关系



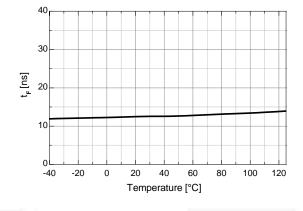
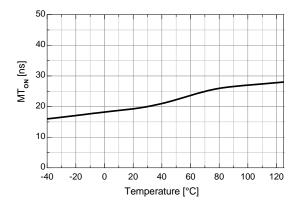


图 8. 导通上升时间与温度的关系

图 9. 导通下降时间与温度的关系



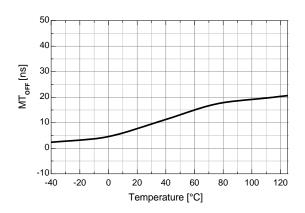
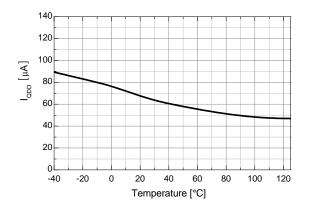


图 10. 导通延时匹配与温度的关系

图 11. 关断延时匹配与温度的关系

# 典型特性 (续)



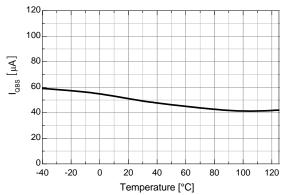
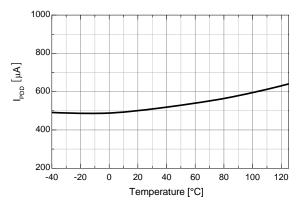


图 12. 静态 V<sub>DD</sub> 电源电流与温度的关系

图 13. 静态 V<sub>BS</sub> 电源电流与温度的关系



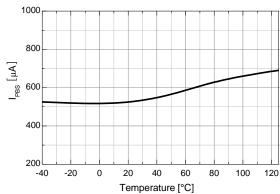
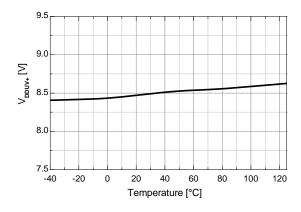


图 14. 工作时 V<sub>DD</sub> 电源电流与温度的关系

图 15. 工作时 V<sub>BS</sub> 电源电流与温度的关系

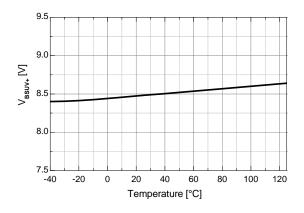


7.5 7.0 -40 -20 0 20 40 60 80 100 1. Temperature [°C]

图 16. V<sub>DD</sub> UVLO+ 与温度的关系

图 17. V<sub>DD</sub> UVLO- 与温度的关系

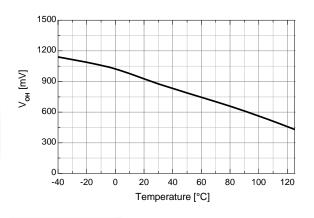
# 典型特性(续)



9.0 8.5 7.5 7.0 -40 -20 0 20 40 60 80 100 120 Temperature [°C]

图 18. V<sub>BS</sub> UVLO+ 与温度的关系

图 19. V<sub>BS</sub> UVLO- 与温度的关系



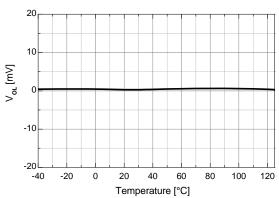
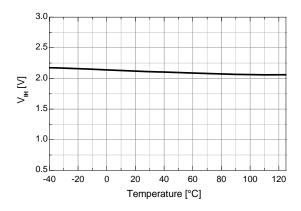


图 20. 高电平输出电压与温度的关系

图 21. 低电平输出电压与温度的关系



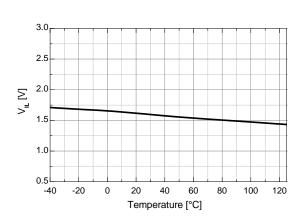
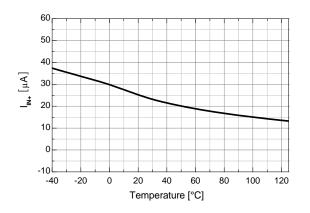


图 22. 逻辑高输入电压与温度的关系

图 23. 低输入电压与温度的关系

# 典型特性(续)



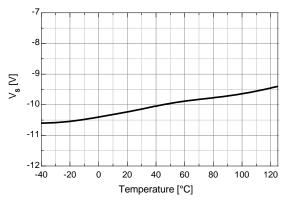


图 24. 逻辑输入高偏置电流与温度的关系

图 25. 容许的负 V<sub>S</sub> 电压与温度的关系

# 开关时间定义

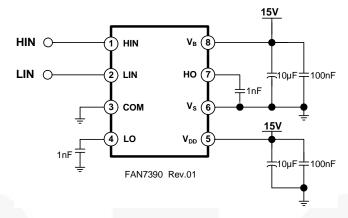


图 26. 开关时间测试电路 (参考 8-SOP)

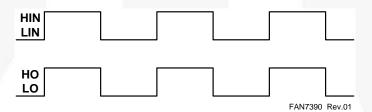


图 27. 输入/输出时序图

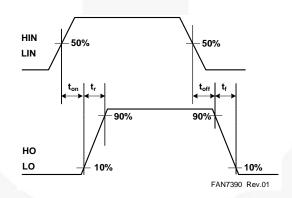


图 28. 开关时间波形定义

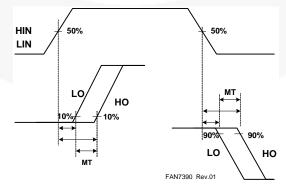


图 29. 开关匹配波形定义

#### 物理尺寸

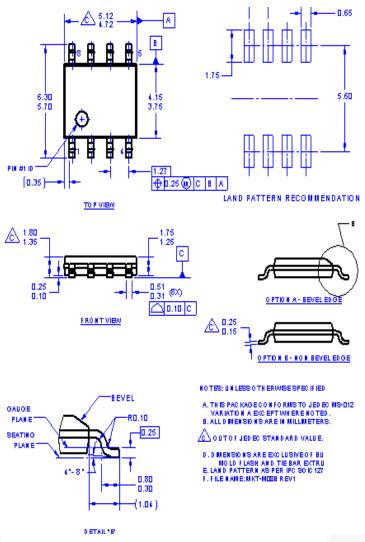
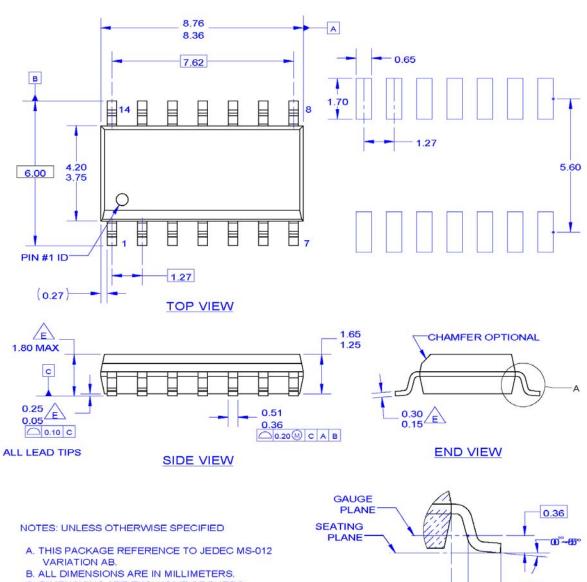


图 30. 8- 引脚小尺寸封装 (SOP)

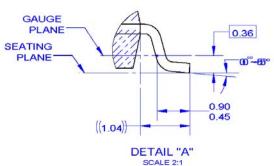
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### 物理尺寸(续)



- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-1994.
- E OUT OF JEDEC STANDARD VALUE.
- F. LAND PATTERN STANDARD: SOIC127P600X145-14M.
- G. FILE NAME: MKT-M14C REV2



#### 图 31. 14 引脚小尺寸封装 (SOP)

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